



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

Part Number: KA3030BR34-S2

Blue

### Features

- Size (mm): 3.0x3.0x0.6
- Suitable for all SMD assembly and solder process.
- Available on tape and reel.
- White SMD package, silicone resin.
- Moisture sensitivity level : level 3
- RoHS compliant.

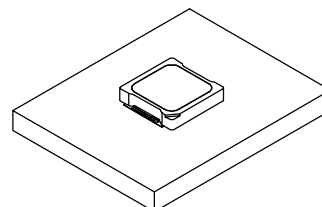
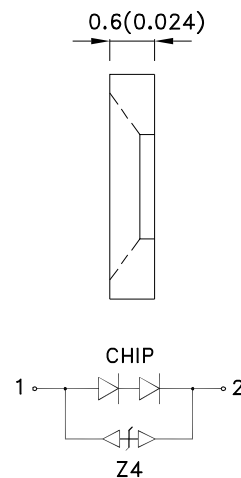
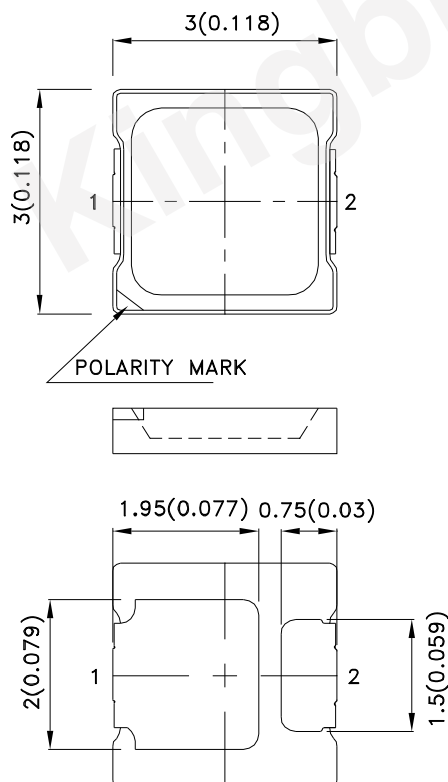
### Descriptions

- The Blue source color devices are made with InGaN Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipment and machinery must be electrically grounded.

### Applications

- LCD TV / Monitor Backlight.
- Architectural lighting.
- Decorative lighting.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



## Handling Precautions

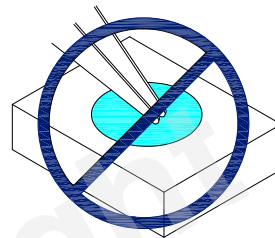
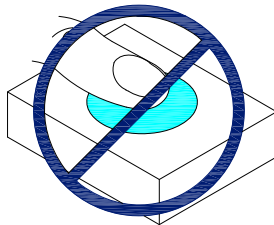
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

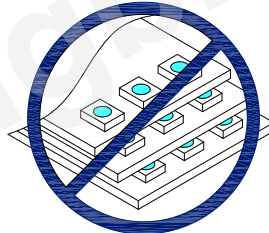
1. Handle the component along the side surfaces by using forceps or appropriate tools.



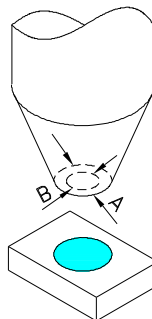
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

## Selection Guide

Part No.	Emitting Color	Lens Type	$\Phi_v$ (lm) [2] @ 100mA		Viewing Angle [1]
			Min.	Typ.	2 $\theta$ 1/2
KA3030BR34-S2	Blue(InGaN)	Water Clear	7.2	10	120 °

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
3. Luminous flux value is traceable to CIE127-2007 standards.

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit
Power dissipation	P <sub>D</sub>	1320	mW
Junction temperature[1]	T <sub>J</sub>	110	°C
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>op</sub>	-40 To +85	°C
Storage Temperature	T <sub>stg</sub>	-40 To +85	°C
DC Forward Current [1]	I <sub>F</sub>	200	mA
Peak Forward Current [2]	I <sub>FM</sub>	400	mA
Electrostatic Discharge Threshold (HBM)		8000	V
Thermal resistance [1](Junction/ambient)	R <sub>th j-a</sub>	75	°C/W
Thermal resistance (Junction/solder point)	R <sub>th j-s</sub>	20	°C/W

Notes:

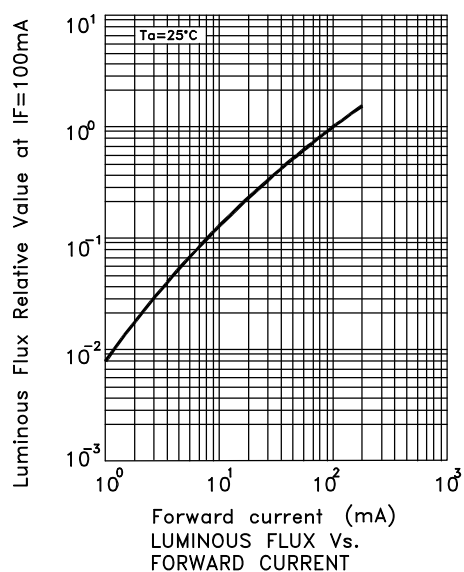
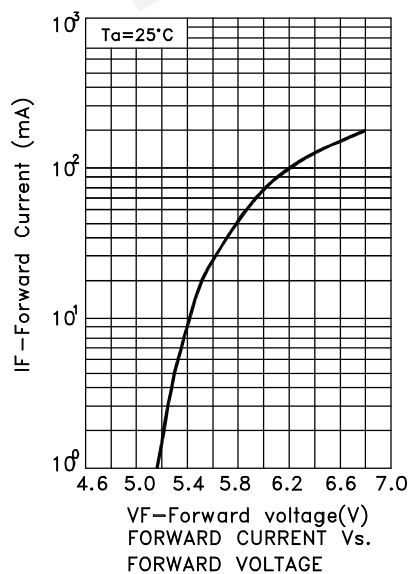
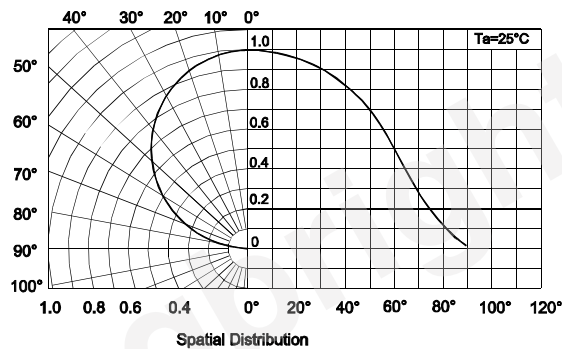
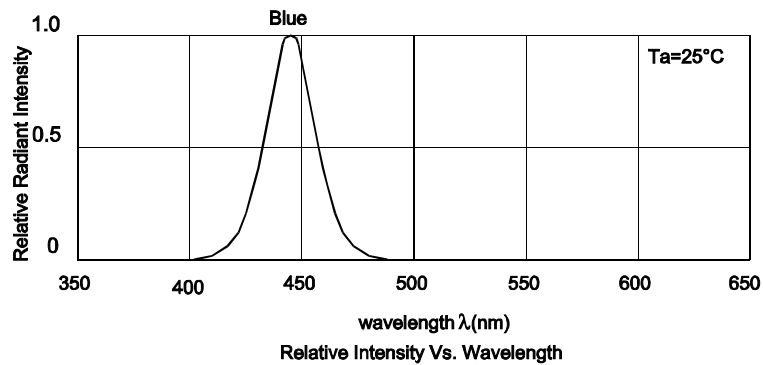
1. Results from mounting on FR4 PC board, Metal-core PCB is recommended for low thermal resistance.
2. 1/10 Duty Cycle, 0.1ms Pulse Width.
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

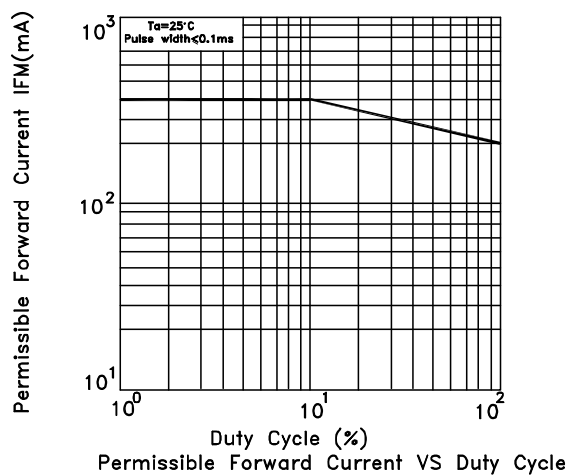
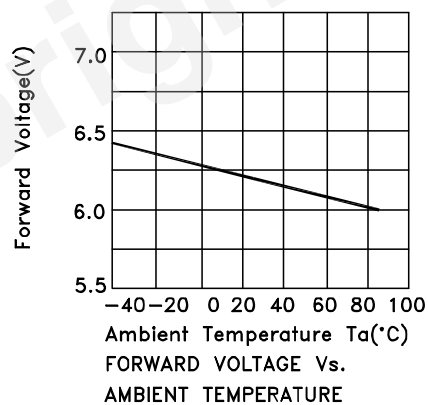
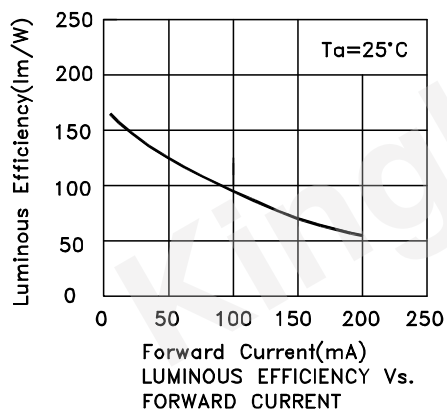
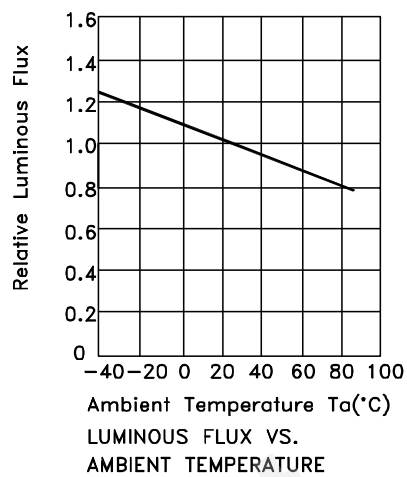
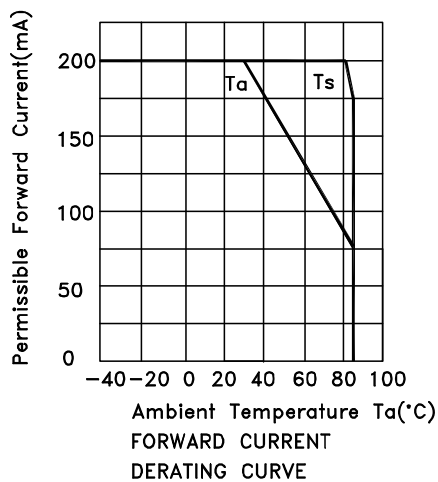
## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit
Wavelength at peak emission I <sub>F</sub> =100mA [Typ.]	$\lambda_{peak}$	445	nm
Dominant Wavelength I <sub>F</sub> =100mA [Typ.]	$\lambda_{dom}$ [1]	450	nm
Spectral bandwidth at 50%F <sub>REL</sub> MAX I <sub>F</sub> =100mA [Typ.]	$\Delta\lambda$ 1/2	25	nm
Forward Voltage I <sub>F</sub> = 100mA [Min.]	V <sub>F</sub> [2]	5.8	V
Forward Voltage I <sub>F</sub> = 100mA [Typ.]		6.2	
Forward Voltage I <sub>F</sub> = 100mA [Max.]		6.6	
Allowable Reverse Current [Max.]	I <sub>R</sub>	85	mA
Temperature coefficient of $\lambda_{peak}$ I <sub>F</sub> = 100mA, -10°C ≤ T ≤ 85°C [Typ.]	TC $\lambda_{peak}$	0.03	nm/°C
Temperature coefficient of $\lambda_{dom}$ I <sub>F</sub> = 100mA, -10°C ≤ T ≤ 85°C [Typ.]	TC $\lambda_{dom}$	0.04	nm/°C
Temperature coefficient of V <sub>F</sub> I <sub>F</sub> = 100mA, -10°C ≤ T ≤ 85°C [Typ.]	TC <sub>V</sub>	-2.6	mV/°C

Notes:

1. The dominant Wavelength ( $\lambda_d$ ) above is the setup value of the sorting machine. (Tolerance  $\lambda_d$  : ±1nm. )
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

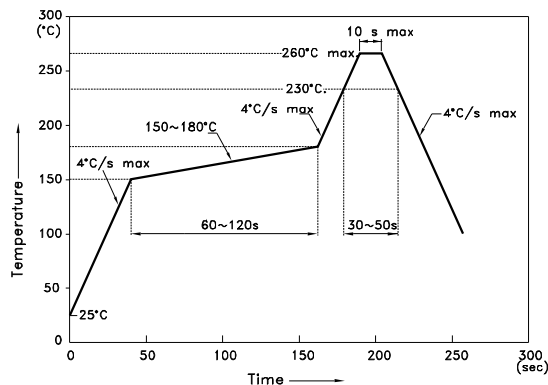




## KA3030BR34-S2

Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

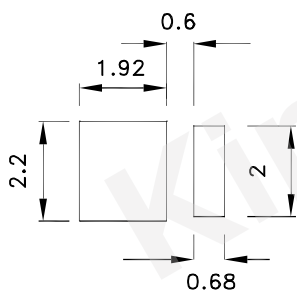
Reflow Soldering Profile For Lead-free SMT Process.



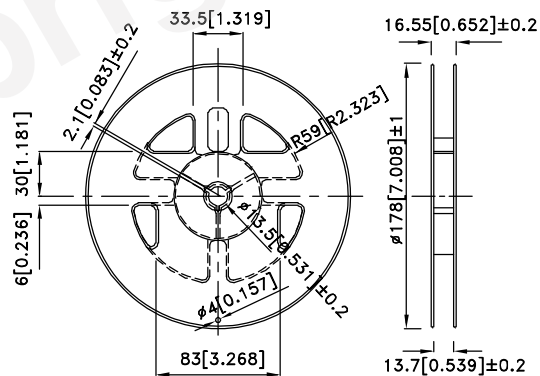
NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (+/-5^{\circ}\text{C})$ . The maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

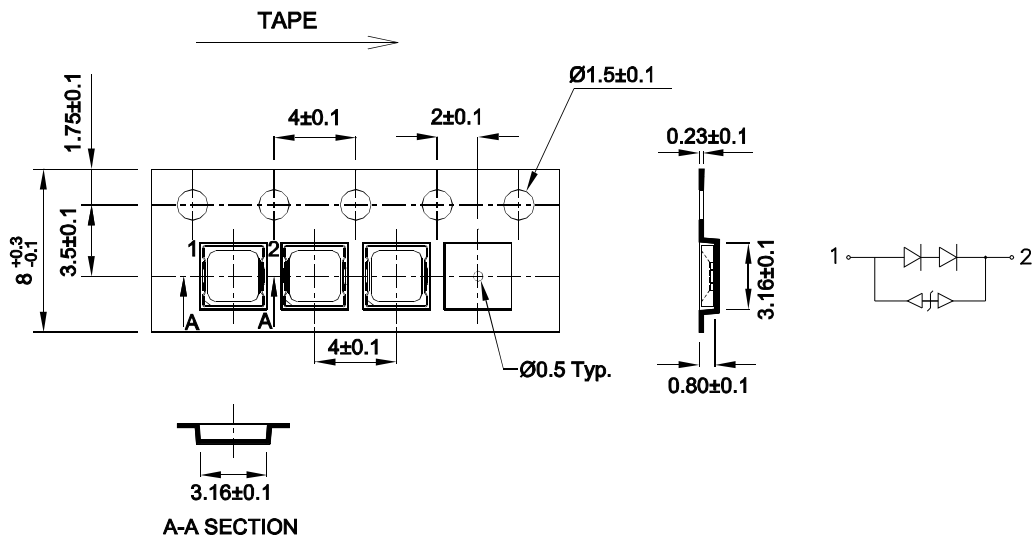
### Recommended Soldering Pattern (Units : mm; Tolerance: $\pm 0.1$ )



### Reel Dimension

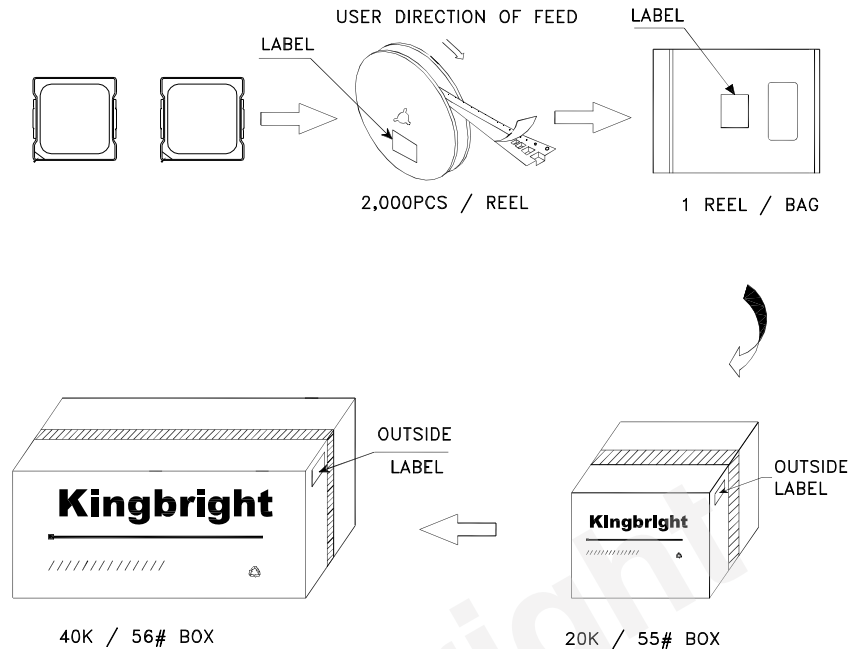



### Tape Dimensions (Units : mm)



## PACKING & LABEL SPECIFICATIONS

KA3030BR34-S2



<b>Kingbright</b>	
P/N0: KA3030xxx	
QTY: 2,000 pcs	Q.C. <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">Q C XX XX XXXX PASSED</span>
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

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